wherein the back plate includes a plurality of spaced holes extending therethrough and wherein the infrared-absorbing material forms a plurality of stakes connected to the inner surface of the front panel and extending through the plurality of spaced holes and wherein the heated infrared-absorbing material forms a plurality of solid connectors after the step of cooling.

## Remarks

In the Advisory Action mailed August 24, 2001 in the parent case (Serial No. 09/305,532), the Examiner objected to claim 3 because it was based on rejected claim 1. Applicants have amended claim 1 to include all the limitations of claim 3 and therefore believe that claim 1 is in condition for allowance which allowance is respectfully requested.

Claim 3 has been cancelled.

Original claims 2 and 4 which depend from claim 1 are now also in condition for allowance.

If the Examiner believes that a telephone conference will advance prosecution of this application, such a conference is highly encouraged at the convenience of the Examiner.

Respectfully submitted,

**JASON T. MURAR, et al**

By _____

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Date: November 20, 2001

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Attachment

# VERSION WITH MARKINGS TO SHOW CHANGES MADE

## In The Specification

Please amend the specification by inserting before the first line the following sentence:

This is a continuation of copending application Serial No. 09/305,531filed on May 5, 1999,which is related to U.S. Patent No. 6,251,202 entitled "Method And System For Bonding Plastic Parts Together" issued on June 26, 2001 and filed on the same date as the parent application now issued as U.S. Patent No. 6,251,202 on June 26, 2001.

Please replace the Specification paragraphs as shown below.

Please replace the paragraph beginning on page 1, at line 17 with the paragraph shown below:

U.S. Patent No. 5,750,[4]970 discloses a method of dielectrically heating an adhesive which, in turn, bonds plastic parts together.

Please replace the paragraph on page 6, at line 18, with the paragraph shown below:

Referring now to Figure 1, there is illustrated a system, generally indicated at 10, for manufacturing an air bag cover assembly, generally indicated at 12 in Figures 3 and 4. The assembly 12 typically includes an air bag cover, generally indicated at 14, having a front panel 16. The assembly 12 also includes a back plate 18, a switch in the form of a membrane switch 20 and infrared-absorbing material in the form of a plurality of stakes 22 connected to the inner surface 26 of the front panel 16. The stakes 22 extend through the plurality of spaced holes [24] 26 formed completely through the back plate 18.

## In the Claims

Please amend claim 1 as shown below. Please cancel claim 3.

1. (Amended) A method of manufacturing an air bag cover assembly, the method comprising:

providing a front panel, a back plate, a switch and infrared-absorbing material separate from either the front panel or the back plate;

positioning the front panel and the back plate so that inner surfaces of the front panel and the back plate define a switch pocket therebetween;

positioning the switch in the switch pocket;

directing infrared radiation at the infrared-absorbing material for a time sufficient to heat the infrared-absorbing material to a desired temperature;

controlling the amount of heat applied to the infrared-absorbing material by the infrared radiation; [and]

cooling the heated infrared-absorbing material, the cooled material fixedly securing the back plate to the front panel[,]; and

wherein the back plate includes a plurality of spaced holes extending therethrough and wherein the infrared-absorbing material forms a plurality of stakes connected to the inner surface of the front panel and extending through the plurality of spaced holes and wherein the heated infrared-absorbing material forms a plurality of solid connectors after the step of cooling.